



## Material Content Data Sheet



<b>Sales Product Name</b>		BFR 460L3 E6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000373257						
<b>Package</b>		PG-TSLP-3-1		<b>Weight*</b>		0.54 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.09		856	
	noble metal	gold	7440-57-5	0.002	0.33		3321	
	inorganic material	silicon	7440-21-3	0.016	2.90	3.32	28953	33130
leadframe	non noble metal	nickel	7440-02-0	0.071	13.12	13.12	131215	131215
wire	noble metal	gold	7440-57-5	0.011	1.93	1.93	19332	19332
encapsulation	organic material	carbon black	1333-86-4	0.004	0.79		7879	
	plastics	epoxy resin	-	0.058	10.64		106369	
	inorganic material	silicondioxide	60676-86-0	0.366	67.36	78.79	673667	787915
leadfinish	noble metal	gold	7440-57-5	0.008	1.42	1.42	14204	14204
plating	noble metal	gold	7440-57-5	0.008	1.42	1.42	14204	14204
*deviation	< 10%		Sum in total:			100,00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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